

SPECIFICATION SHEET

SPECIFICATION SHEET NO.	N0207-XF25M00000S001
DATE	Feb. 07, 2021
REVISION	A0
DESCRIPTION	SMD Crystal, Seam seal, 3225 Type, 4 pads, 25.0000MHz, +/-50ppm, CL 20pF, Stability +/-50ppm @Operating Temp. Range -40°C ~+85°C, ESR 40 ohm Max, Tape/Reel, Reflow Profile Condition 260 °C Max. RoHS/RoHS III compliant
CUSTOMER	
CUSTOMER PART NUMBER	
CROSS REF. PART NUMBER	
ORIGINAL PART NUMBER	TGS CM32 25M0A50-20-50-40-40TLF
PART CODE	XF25M00000S001

VENDOR APPROVE

Issued/Checked/Approved



DATE: Feb. 07, 2021

CUSTOMER APPROVE

DATE:

SMD CRYSTAL 3225 TYPE 4 PADS

MAIN FEATURE

- SMD Crystal, Seam Seal, L3.2*W2.5*H0.7mm, 4 pads
- Low cost, High precision, High frequency stability
- Reflow Profile Condition 260 °C Max.
- Cross more competitors part
- RoHS/RoHS III compliant



APPLICATION

- Bluetooth, wireless communication set
- Communication Electronics

PART CODE GUIDE

RFQ

[Request For Quotation](#)

XF	25M00000	S	001
1	2	3	4

- 1) XF: Part family Code for SMD Crystal, Seam Seal, L3.2*W2.5*H0.7mm, 4 pads (CM32)
- 2) 25M00000: Frequency range code for 25.0000MHz
- 3) S: SMD type, Package Tape/Reel, 1000pcs/Reel
- 4) 001: Specification code for original part No.: **TGS CM32 25M0A50-20-50-40-40TLF**

MORE FREQUENCY RANGE AVAILABLE (MHz)

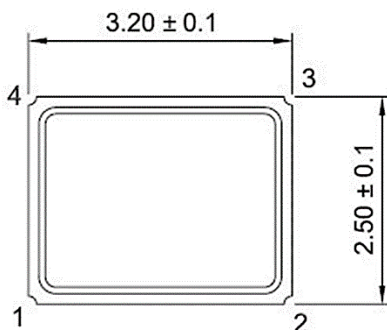
8.0000	11.0592	12.000	14.31818	16.0000	20.0000	24.000	24.545454	25.0000	26.000
27.0000	30.000	32.000	40.0000	50.0000					

DIMENSION (Unit: mm, Tol. +/-0.15mm)

Image for reference

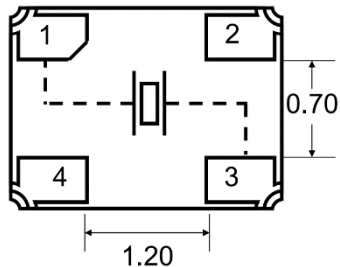


CM32



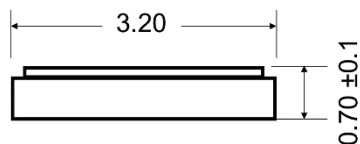
Marking

Line 1: Company Code + CL value
Line 2: Freq. Range+ QC Code (A~Z)

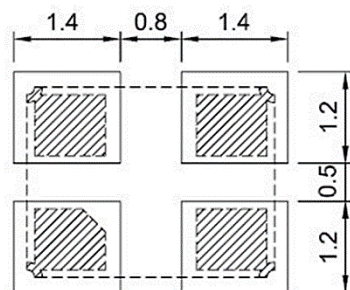


Connection

#1 Crystal
#2 Ground
#3 Crystal
#4 Ground



Recommend Pad Layout



SMD CRYSTAL 3225 TYPE 4 PADS

ELECTRICAL PARAMETERS

Parameter		Part No. Symbol	Units	Value			Condition
				Min.	Typical	Max.	
Original Manufacturer		TGS	TGS Crystals				
Holder Type		CM32	SMD Crystal, Seam Seal, L3.2*W2.5*H0.7mm, 4 pads				
Frequency Range		25M0	MHz	25.000			
Mode of Oscillation		A		AT Fundamental			
Frequency Tolerance		50	ppm	-50		+50	@25°C
Load Capacitance		-20	pF	20			
Stability over Operation Temperance		-50	ppm	-50		+50	
Operation Temperance		-40	°C	-40		+85	
Storage Temperance			°C	-55		+125	
Equivalent Series Resistance (ESR)		-40	Ω			40	
Drive Level			μW			100	
Shunt Capacitance (C0)			pF	0		7.0	
Motional Capacitance (C1)			fF	N/A			
DLD2			Ω	N/A			
FLD2			ppm	N/A			
RDL2			Ω	N/A			
SPDB			dB	N/A			
Aging			ppm/year			±3	@1 st year
Insulation Resistance			MΩ	500			@100Vdc ± 15Vdc
Others	Package	T	Tape/Reel				
	RoHS Status	LF	RoHS III compliant				
	Add Value		N/A				
	Internal Control Code 🌟		N/A				

Note: 1) Original Part Number: **TGS CM32 25M0A50-20-50-40-40TLF**
2) * Internal Control Code- 2 letter or digits; Blank: N/A

SMD CRYSTAL 3225 TYPE 4 PADS

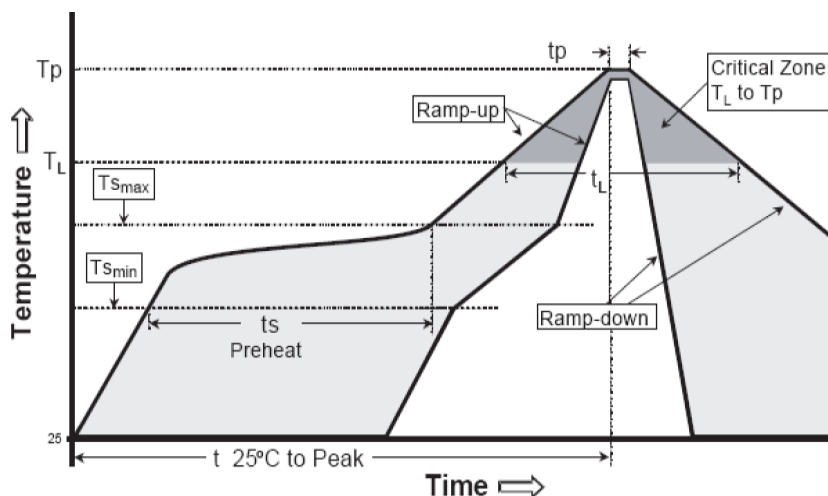
RELIABILITY

Test Items	Test Method And Conditions	Reference Documents
High Temperature High Humidity Storage	Temperature: 85°C±3°C Relative Humidity:85%RH Time: 96 Hours	JIS C5023
High Temperature Storage	Temperature: 125°C±3°C Time: 96 Hours.	MIL-STD-883E Method 1005.8
Low Temperature Storage	Temperature: -40°C±3°C Time: 96 Hours.	MIL-STD-883E Method 1013
Thermal Shock	Temperature 1: -55°C±5°C Temperature 2: 85°C±5 °C Temperature change between T1 and T2 5 min 10cycles maintain T1 and T2 for 30 minutes each cycle	MIL-STD-202F Method 107 Condition A
Resistance to Solder Heat	Solder Temperature: 260°C±5°C Time: 10±1 Seconds	MIL-STD-202F Method 210E
Solderability	The solder pot temperature is 245±5°C , dwell time 5±0.5sec	J-STD-002B
Drop Test	3 Times Free Fall from 50cm height table to 3cm thickness hard wood board	J-STD-002B
Mechanical Shock	Half sine wave,1000 G 3 Times for all 3 directions(X,Y Z)	MIL STD 202F Method 213B
Vibration	Frequency Range: 10Hz ~ 55Hz Amplitude: 0.75mm 2 Hours in each direction, total 6 Hours	MIL-STD-883E Method 2007.3
Leakage Test	Take measurements with a helium Leakage detector Leakage Rate≤1×10 ⁻³ Pa cm ³ /s	MIL-STD-883E

SMD CRYSTAL 3225 TYPE 4 PADS

SUGGESTED REFLOW PROFILE (For Reference Only)

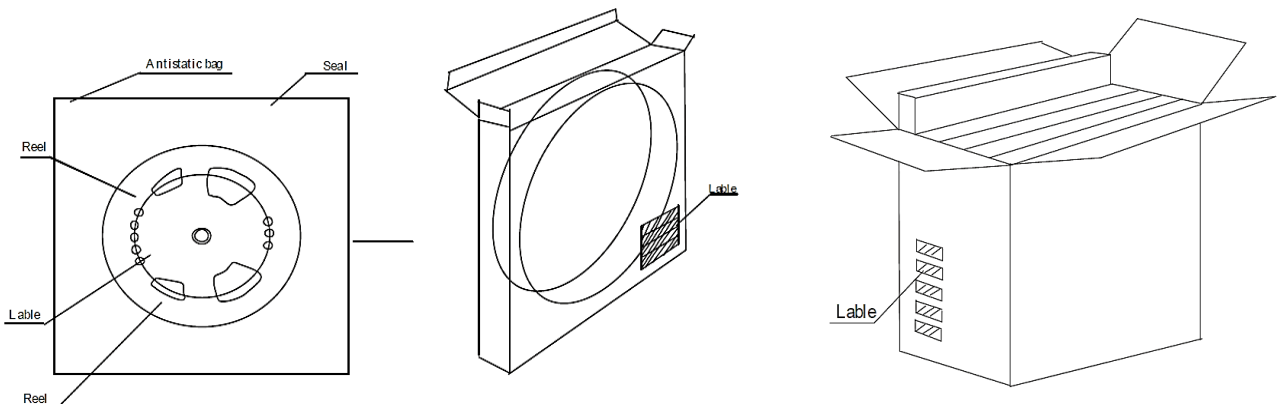
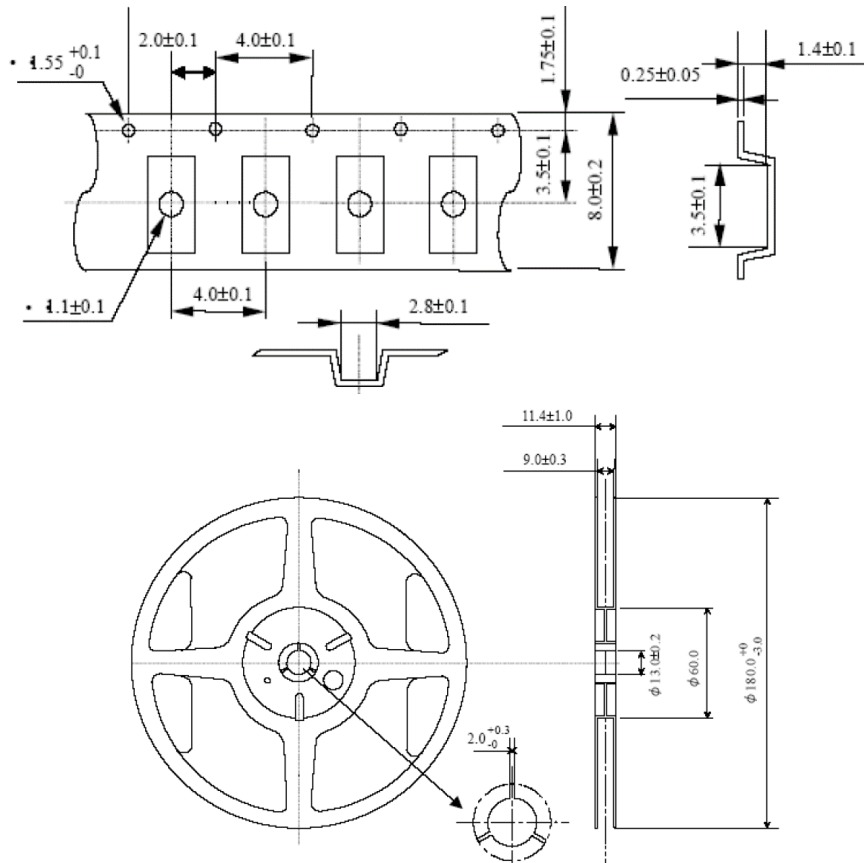
Total time: 200 Sec. Max. Solder melting point: 220°C



Profile Feature		Pb-Free Assembly
Average Ramp-up Rate (Ts Max to Tp)		3°C/second Max
Preheat	Temperature Min (Ts Min.)	125°C
	Temperature Max (Ts Max.)	200°C
	Time (ts Min. to ts Max.)	60 ~ 180 seconds
Time maintained above	Temperature (T_L)	217°C
	Time (t_L)	60 ~ 150 seconds
Peak/Classification Temperature (Tp)		260 °C
Time within 5°C of actual Peak Temperature (tp)		20 ~ 40 seconds
Ramp-down rate		6 °C /Second Max.
Time 25 °C to Peak Temperature		8 minutes Max.
Suggest reflow times		3 Times Max.

TAPE/REEL (Unit: mm)

All Devices are packed in accordance with EIA standard RS-481-2 and specifications., 3000pcs/Reel



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